

L Number	Hits	Search Text	DB	Time stamp
3	2700922	wafer wafers substrate substrates semiconductor semiconductors	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 09:43
4	47591	cmp (chemical adj mechanical adj polishing)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:53
5	183262	rinse rinsing rinsed rinses	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:54
6	0		USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:56
7	0		USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:56
8	625	((wafer wafers substrate substrates semiconductor semiconductors) same (cmp (chemical adj mechanical adj polishing)) same (rinse rinsing rinsed rinses)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 08:04
9	19203	((wafer wafers substrate substrates semiconductor semiconductors) with (cmp (chemical adj mechanical adj polishing))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:56
10	466	((wafer wafers substrate substrates semiconductor semiconductors) with (cmp (chemical adj mechanical adj polishing))) same (rinse rinsing rinsed rinses)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:57
11	2206125	silicon silica glass quartz	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:57
12	480	((wafer wafers substrate substrates semiconductor semiconductors) same (cmp (chemical adj mechanical adj polishing)) same (rinse rinsing rinsed rinses)) and (silicon silica glass quartz)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:57
13	745	polyoxyalkylene adj alkyl adj ether	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:58
14	5	(rinse rinsing rinsed rinses) with (polyoxyalkylene adj alkyl adj ether)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 07:58
15	64178	451/\$.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 08:05
16	163	((wafer wafers substrate substrates semiconductor semiconductors) same (cmp (chemical adj mechanical adj polishing)) same (rinse rinsing rinsed rinses)) and 451/\$.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 08:05

17	810941	pH	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 08:05
18	54	((wafer wafers substrate substrates semiconductor semiconductors) same (cmp (chemical adj mechanical adj polishing)) same (rinse rinsing rinsed rinses)) and 451/\$.ccls.) and pH	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 08:05
19	48	(wafer wafers substrate substrates semiconductor semiconductors) same (rinse rinsing rinsed rinses) same (pH near3 reduc\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 08:53
20	46	((wafer wafers substrate substrates semiconductor semiconductors) same (rinse rinsing rinsed rinses) same (pH near3 reduc\$)) not (((wafer wafers substrate substrates semiconductor semiconductors) same (cmp (chemical adj mechanical adj polishing)) same (rinse rinsing rinsed rinses)) and 451/\$.ccls.) and pH)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 09:42
21	820702	(wafer wafers substrate substrates semiconductor semiconductors) and (silicon silica glass quartz)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 09:43
22	48212	wafer wafers substrate substrates semiconductor semiconductors	USOCR	2004/07/27 09:43
23	25182	(wafer wafers substrate substrates semiconductor semiconductors) and (silicon silica glass quartz)	USOCR	2004/07/27 09:44
24	25182	(wafer wafers substrate substrates semiconductor semiconductors) and ((wafer wafers substrate substrates semiconductor semiconductors) and (silicon silica glass quartz))	USOCR	2004/07/27 09:44
25	123	((wafer wafers substrate substrates semiconductor semiconductors) and (silicon silica glass quartz)) and 451/\$.ccls.	USOCR	2004/07/27 09:44